THE MISSOURI INNOVATION CAMPUS

FAX 816-347-9574

Elliott@ucmo.edu

Student Memo of Understanding

(Effective January 2025)

Student Name____

In applying for entrance into The Missouri Innovation Campus program for the 2025-2026 school year, I agree to the following guidelines:

1. I will maintain a **95% attendance record**. In the event that my attendance drops below that level during a semester of attendance, I will request an **Attendance Waiver Conference**. I understand that my continued attendance will be determined by Attendance Waiver approval.
2. I will maintain an acceptable conduct record at The Missouri Innovation Campus, my internship placement, and my sending school. I understand that suspensions from either Summit Technology Academy or my sending school may result in removal from The Missouri Innovation Campus program.
3. I will **maintain a minimum 2.0 GPA** in my postsecondary coursework. Failure to do so will result in removal from the program at the end of the semester. MIC Business Partners may require a higher GPA for internship placement. **I will maintain a 3.0 GPA during my high school coursework.**
4. Metropolitan Community College tuition will be paid through the direct bill process to The Missouri Innovation Campus. Textbooks and other instructional materials at MCC are the responsibility of the student. Any scholarship, grant aid or A+ funds will be applied to the MCC tuition before MIC funding.
5. Tuition, textbooks and other instructional materials or fees for the last two years at UCM are the responsibility of the student.
6. AP and IB course exam fees will be reimbursed upon verification of the appropriate score for earning college credit. Student/Parent will pay for the exam fee, and then submit a receipt and transcripted grade (Score) to The Missouri Innovation Campus for reimbursement.
7. Any student taking college coursework through another postsecondary institution other than MCC or UCM will be reimbursed the appropriate number of credit hours at the Metropolitan Community College tuition rate. Students/Parents will pay for the dual credit, and then submit a receipt and transcript to The Missouri Innovation Campus for reimbursement.
8. Any course that is failed, dropped or re-taken by The Missouri Innovation Campus student will result in the student paying for the course retake. If the student drops the MIC program during the semester, they will be responsible for reimbursing MCC and/or UCM for the tuition.
9. A student, when eligible, must procure an internship placement with an MIC Business Partner to participate in the MIssouri Innovation Campus Program unless there are fewer partner requests for interns than our intern numbers. **I understand that the MIC Internship is a three-year commitment and if I transfer out of the MIC Program once placed in an internship, I will pay UCM the $2000.00 MIC Intern Placement Fee.** Being dismissed from the internship due to performance issues results in the student being released from the MIC Program. I also understand that being released from the MIC Program voids the internship with the MIC Business Partner.
10. While in attendance at the internship site, I will conform to the dress code and other policies in effect for the respective company. This will include any program-related work experiences in which I participate.
11. **Transportation to the internship site is the responsibility of the student.**
12. If removed from The Missouri Innovation Campus program for any reason, I understand that I may not receive credit for courses taken at my sending school, Metropolitan Community College or University of Central Missouri. I also understand that I may not be able to enroll in coursework at my sending school until the next enrollment period. I understand that a half-day semester program earns 1.5 units of high school credit; a year-long program earns 3 units of credit.
13. By signing this form, I allow my educational records to be released to my home school, Metropolitan Community College, University of Central Missouri and the MIC Business Partners for inclusion in my file.

By signing this agreement, I acknowledge that I will abide by the above guidelines. Failure to do so may result in probation or dismissal from the program. (turn form over to complete page 2)

______________________________________Date__________ *Student signature*	______________________________________Date__________ *High School Counselor signature*
______________________________________Date__________ *Parent/Legal Guardian Signature*	______________________________________Date__________ *Missouri Innovation Campus Director Signature*

Please provide the following information for MIC Program use:

Student Phone Number:____

Student Email Address:____

Parent/Guardian Phone Number:____

Parent/Guardian Email Address:____

Student/Parent Home Address:____

Office Use Only:

Engineering Design Technology Cohort F2025-29__________
Data Science F2025-29 __________________
Software Development/Computer Science Cohort F2025-29__________
Software Engineering Cohort F2025-29__________
Cybersecurity Cohort F2025-29_____________
Big Data/Business Analytics F2025-29____________
Computer Information Systems F2025-29____________